

## WHAT IS CLAIMED IS:

SUB A1 > 1. A flexible printed circuit board comprising a component mount section, which an electronic component is mounted on, and a cable section, which connects to the component mount section;

circuit patterns being provided on the cable section, and covered by a soft laminated adhesive.

2. The flexible printed circuit board as described in Claim 1, the laminated adhesive comprising an adhesive which maintains an average thickness at the time of lamination.

SUB A2 > 3. The flexible printed circuit board as described in Claim 1, the laminated adhesive comprising a polyamide adhesive.

4. The flexible printed circuit board as described in Claim 1, the laminated adhesive comprising an acrylic adhesive.

SUB A3 > 5. A method for manufacturing a flexible printed circuit board having a component mount section, which comprises an outer-layer material laminated on an inner-layer material with an insulating cover therebetween, and a cable section, which comprises the inner-layer material covered by the insulating cover and connects to the component mount section, the method comprising the step of:

covering the inner-layer material of the component mount section and the cable section with a soft laminated adhesive.

Add A4 >

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